



## Dual N-channel 20V, TSSOP-8 MOSFET 双 N-沟道场效应管

### ■ Features 特点

Low on-resistance and maximum DC current capability 低导通电阻和最大直流电流能力

Super high density cell design 超高元胞密度设计

$R_{DS(ON)} \leq 20m\Omega @ V_{GS}=4.5V$

$R_{DS(ON)} \leq 23m\Omega @ V_{GS}=2.5V$

### ■ Applications 应用

Power Management in Note book 笔记本电源管理

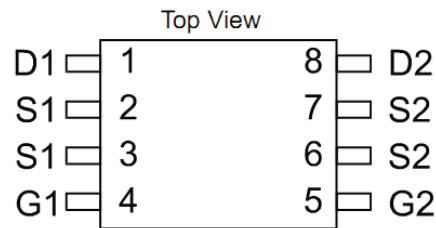
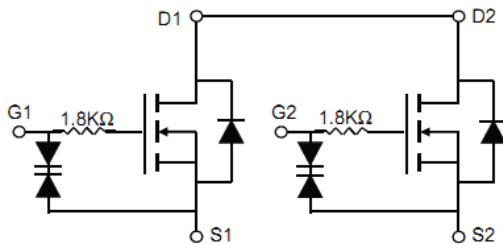
Portable Equipment 便携式设备

Battery Powered System 电池电源系统

DC/DC Converter 直流/直流变换

Load Switch 负载开关应用

### ■ Internal Schematic Diagram 内部结构



### ■ Absolute Maximum Ratings 最大额定值

Characteristic 特性参数	Symbol 符号	Max 最大值	Unit 单位
Drain-Source Voltage 漏极-源极电压	$BV_{DSS}$	20	V
Gate- Source Voltage 栅极-源极电压	$V_{GS}$	$\pm 8$	V
Drain Current (continuous) 漏极电流-连续	$I_D$	7	A
Drain Current (pulsed) 漏极电流-脉冲	$I_{DM}$	25	A
Total Device Dissipation 总耗散功率	$P_{TOT}$ (at $T_C = 25^\circ C$ ) (at $T_C = 70^\circ C$ )	1.5 1	W
Thermal Resistance Junction-Ambient 热阻	$R_{\theta JA}$	83	$^\circ C/W$
Junction/Storage Temperature 结温/储存温度	$T_J, T_{stg}$	-55~150	$^\circ C$



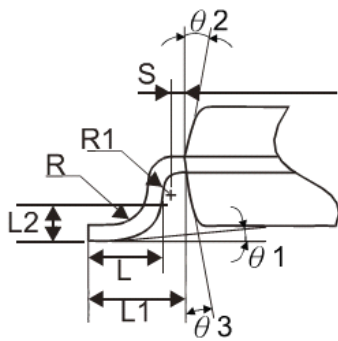
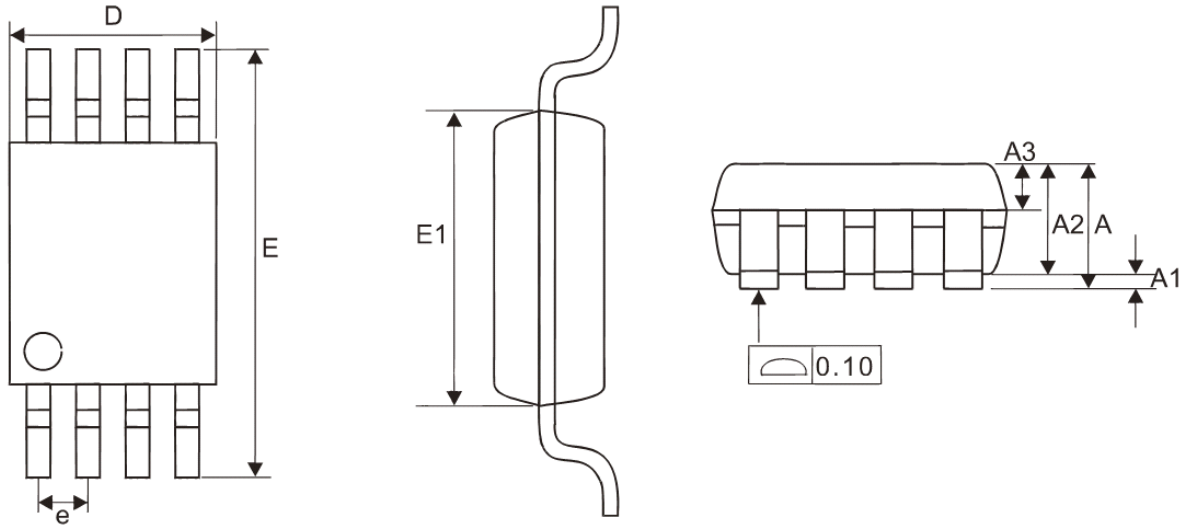
**Electrical Characteristics 電特性**

( $T_A=25^{\circ}\text{C}$  unless otherwise noted 如無特殊說明，溫度為  $25^{\circ}\text{C}$ )

Characteristic 特性參數	Symbol 符號	Min 最小值	Typ 典型值	Max 最大值	Unit 單位
Drain-Source Breakdown Voltage 漏極-源極擊穿電壓( $I_D=250\mu\text{A}, V_{GS}=0\text{V}$ )	$BV_{DSS}$	20	—	—	V
Gate Threshold Voltage 柵極開啓電壓( $I_D=250\mu\text{A}, V_{GS}=V_{DS}$ )	$V_{GS(th)}$	0.4	—	1.1	V
Zero Gate Voltage Drain Current 零柵壓漏極電流( $V_{GS}=0\text{V}, V_{DS}=20\text{V}$ )	$I_{DSS}$	—	—	1	$\mu\text{A}$
Gate Body Leakage 柵極漏電流( $V_{GS}=\pm 8\text{V}, V_{DS}=0\text{V}$ )	$I_{GSS}$	—	—	$\pm 10$	$\mu\text{A}$
Static Drain-Source On-State Resistance 靜態漏源導通電阻( $I_D=7\text{A}, V_{GS}=4.5\text{V}$ ) ( $I_D=6.5\text{A}, V_{GS}=2.5\text{V}$ )	$R_{DS(ON)}$	—	16 18	20 23	$\text{m}\Omega$
Diode Forward Voltage Drop 內附二極管正向壓降( $I_{SD}=1\text{A}, V_{GS}=0\text{V}$ )	$V_{SD}$	—	—	1	V
Input Capacitance 輸入電容 ( $V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$ )	$C_{ISS}$	—	1295	—	pF
Common Source Output Capacitance 共源輸出電容( $V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$ )	$C_{OSS}$	—	160	—	pF
Reverse Transfer Capacitance 反向傳輸電容 ( $V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$ )	$C_{RSS}$	—	87	—	pF
Gate Source Charge 柵源電荷密度 ( $V_{DS}=10\text{V}, I_D=7\text{A}, V_{GS}=4.5\text{V}$ )	$Q_{gs}$	—	4.2	—	nC
Gate Drain Charge 柵漏電荷密度 ( $V_{DS}=10\text{V}, I_D=7\text{A}, V_{GS}=4.5\text{V}$ )	$Q_{gd}$	—	2.6	—	nC
Turn-On Delay Time 開啓延遲時間 ( $V_{DS}=10\text{V}, I_D=1\text{A}, R_{GEN}=3\Omega, V_{GS}=4.5\text{V}$ )	$t_{d(on)}$	—	280	—	ns
Turn-On Rise Time 開啓上升時間 ( $V_{DS}=10\text{V}, I_D=1\text{A}, R_{GEN}=3\Omega, V_{GS}=4.5\text{V}$ )	$t_r$	—	328	—	ns
Turn-Off Delay Time 關斷延遲時間 ( $V_{DS}=10\text{V}, I_D=1\text{A}, R_{GEN}=3\Omega, V_{GS}=4.5\text{V}$ )	$t_{d(off)}$	—	3760	—	ns
Turn-On Fall Time 開啓下降時間 ( $V_{DS}=10\text{V}, I_D=1\text{A}, R_{GEN}=3\Omega, V_{GS}=4.5\text{V}$ )	$t_f$	—	2240	—	ns



■ DIMENSION 外形封装尺寸



SYMBOL	MILLIMETERS	
	MIN	MAX
A	-	1.20
A1	0.05	0.15
A2	0.90	1.05
A3	0.34	0.54
D	2.90	3.10
E	6.20	6.60
E1	4.30	4.50
e	0.65BSC	
L	0.45	0.75
L1	1.00REF	
L2	0.25BSC	
R	0.09	-
R1	0.09	-
S	0.20	-
$\theta 1$	0°	8°
$\theta 2$	10°	14°
$\theta 3$	10°	14°

Note: 1. Refer to JEDEC MS-012AA.

2. Dimension "D" does not include mold flash, protrusions